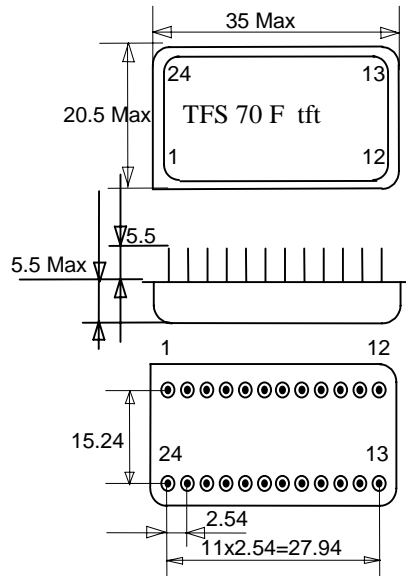


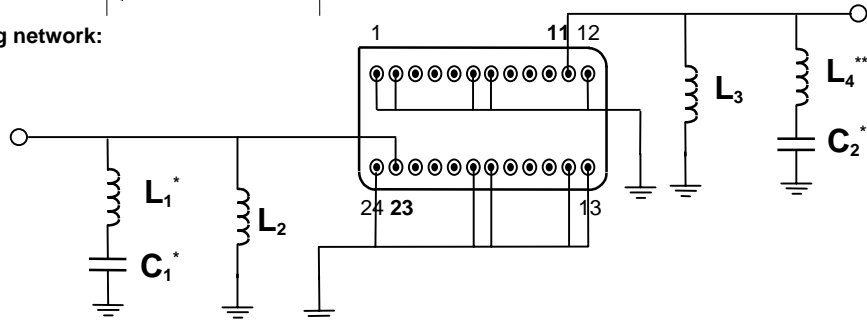


## 3. Package



Pin 23	<b>Input</b>
Pin 24	Input RF Return
Pin 11	<b>Output</b>
Pin 12	Output RF Return
Pin 5-8,17-20	Package Ground

## 4. 50 Ω matching network:



$$L_2 = 217 \pm 5 \text{ nH}$$

$$L_3 = 100 \pm 5 \text{ nH}$$

$$*) L_1 = 465 \pm 10 \text{ nH} \quad C_1 = 70 \text{ pF.}$$

$$1/\sqrt{L_1 C_1} = 2\pi f_1, \quad f_1 = 28.937 \text{ MHz}$$

$$**) L_4 = 200 \pm 10 \text{ nH} \quad C_2 = 10.6 \text{ pF.}$$

$$1/\sqrt{L_4 C_2} = 2\pi f_2, \quad f_2 = 107.375 \text{ MHz}$$

## VI TELEFILTER

Potsdamer Straße 18

D 14 513 TELTOW / Germany

Tel: (+49) 3328 4784-52 / Fax: (+49) 3328 4784-30

E-Mail: tft@telefilter.com

Vectron International, Inc.

267 Lowell Road

Hudson, NH 03051 / USA

Tel: (603) 598-0070 Fax: (603) 598-0075

E-Mail: vti@vtinh.com

## Air reflow temperature conditions

1st and 2nd air reflow profile

<b>Name:</b>	pre-heating periods	main-heating periods	peak temperature
<b>Temperature:</b>	150 °C - 170 °C	over 200 °C	255 °C ± 5 °C
<b>Time:</b>	60 sec. - 90 sec.	20 sec. - 25 sec.	

## Chip-mount air reflow profile

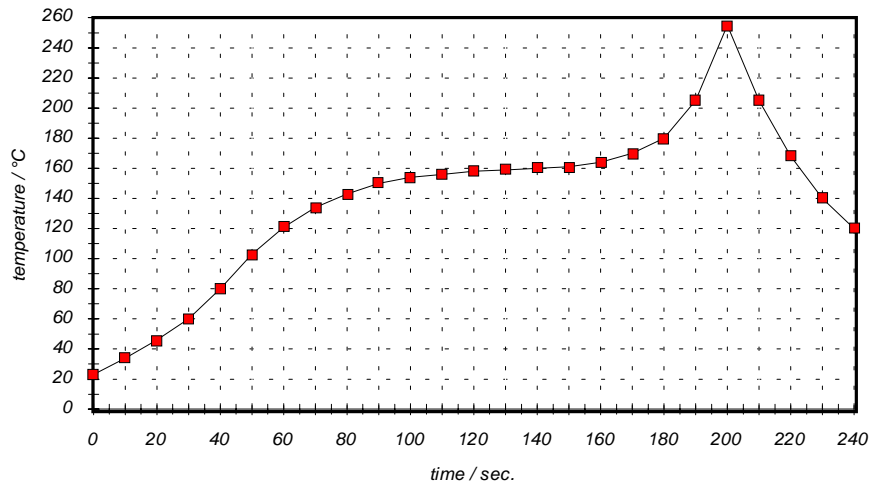


Table for temperature vs. time during the air reflow process

Tolerance of temperatures: ± 5 °C

time / sec.	temperature / °C	time / sec.	temperature / °C
0	23	140	160
10	34	150	161
20	46	160	164
30	60	170	170
40	80	180	180
50	103	190	205
60	121	195	230
70	134	200	255
80	143	205	230
90	150	210	205
100	154	215	180
110	156	220	165
120	158	230	140
130	159	240	120